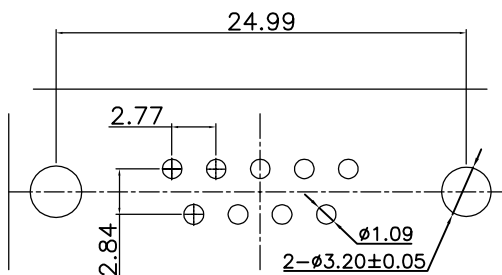
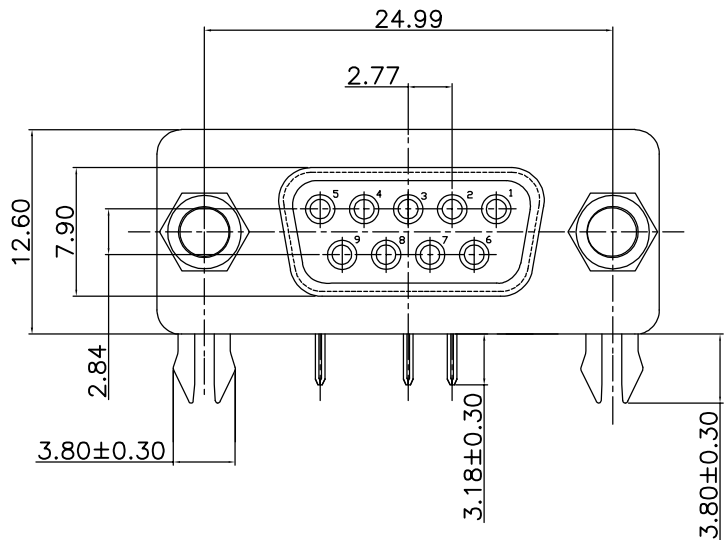


The product using material and processing must conform to the "WI-PZ-001"HSF technical standard control requirements

RoHS



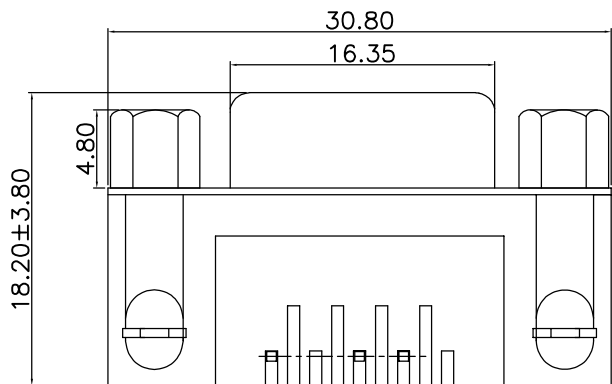
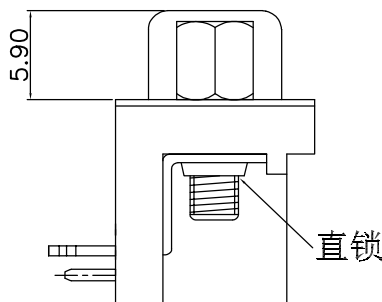
PCB LAYOUT

NOTE:

- 1.MATERIAL SPECIFICATION:
 - 1-1.HOUSING: PBT BLACK.
 - 1-2.CONTACTS: COPPER ALLOY
 - 1-3.SHELL: SPCC
 - 1-4.SCREW: SPCC
 - 1-5.GROUNDING:SPCC
- 2.PLATING:
 - 2-1.CONTACT:
 - SELECTIVE GOLD PLATED ON CONTACT AREA
 - 80u" Min. TIN PLATED OVERALL
 - 50u" Min. NICKEL UNDER-PLATED
 - 2-2.SHELL: 50u" Min. NICKEL PLATED OVERALL
 - 2-3.SCREW: NICKEL PLATED OVERALL
 - 2-4.GROUNDING: TIN PLATED OVERALL.
- 3.MECHANICAL PERFORMANCE:
 - 3-1.MATING FORCE: 5.1Kg.Max.
 - 3-2.UNMATING FORCE: 1.0~4.0Kg.
- 4.ELECTRICAL PERFORMANCE:
 - 4-1.CURRENT RATING: 3A
 - 4-2.VOLTAGE RATING: 250V MAX
 - 4-3.CONTACT RESISTANCE: 25mΩ Max.
 - 4-4.INSULATION RESISTANCE: 5000MΩ MIN
 - 4-5.DIELECTRIC WITHSTANDING VOLTAGE: 1000V AC Min
- 5.ENVIRONMENTAL PERFORMANCE:
 - OPERATING TEMPERATURE: -25°C~+85°C.
- 6.P/N ORDER:

WLDBF9-03 1 X X 0 100

PLATING: 1-G/F
7-Sn
COLOUR: A-BLACK



REV.	REVISION RECORD	DATE	UNIT:mm	GENERAL TOLERANCES		SCALE:	NAME	DATE	PART.NO:	DWG.NO:	
AO	NEW RELEASE	21.01.13		LINEAR	ANGLES	1:1					
			0.00±0.25	X'±3'	DESIGNER	Han_Gao	21.01.13	TITLE:			
			0.00±0.10	X'X' ±2'	DRAWN	Zijun_Huang	21.01.13	DR 9F 90° DIP (仅2.3.5孔位插针)			
			SIZE: A4							REV: A0	SHEET: 1/1